

SERIES: SF500G | **DESCRIPTION:** THERMAL PAD

FEATURES

- 3.5 W/m*K thermal conductivity
- naturally tacky
- silicone based
- electrical isolation
- sizes to match CUI peltier footprints


SPECIFICATIONS

| parameter | test method/conditions/description | min | typ | max | units |
|------------------------------|------------------------------------|------|------------------|-----|----------|
| material | silicone elastomer | | | | |
| color | blue | | | | |
| thickness | ASTM D751 | | 0.5 | | mm |
| specific gravity | ASTM D297 | | 3.0 | | g/cc |
| hardness | ASTM D2240 | 25 | | 80 | shore 00 |
| tensile strength | ASTM D412 | | 25 | | psi |
| continuous use temperature | | -58 | | 200 | °C |
| dielectric breakdown voltage | ASTM D149 | 2500 | | | V |
| dielectric constant [1 MHz] | ASTM D150 | | 6.0 | | |
| volume resistivity | ASTM D257 | | 10 ¹³ | | Ω*cm |
| thermal conductivity | ASTM D5470 | | 3.5 | | W/m*K |
| RoHS | yes | | | | |

PART NUMBER KEY
SF500G - XXXX 05

Base Number

Footprint Size (mm):

 10x10 = 1010
 15x15 = 1515
 15x30 = 1530
 20x20 = 2020
 20x40 = 2040
 26.25x50 = 2650
 30x12 = 3012
 30x30 = 3030
 31.25x30 = 3130
 40x40 = 4040
 41.25x45 = 4145
 50x50 = 5050
 70x70 = 7070

REVISION HISTORY

| rev. | description | date |
|------|------------------------------|------------|
| 1.0 | initial release | 11/02/2018 |
| 1.01 | brand update | 03/24/2020 |
| 1.02 | logo, datasheet style update | 08/05/2022 |

The revision history provided is for informational purposes only and is believed to be accurate.